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ThinkCP(TM) Technologies to Release Mobile 3.75 Terabyte SATA RAID System at 2007 GSA Expo in Orlando, Florida

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IRVINE, Calif., May 15 /PRNewswire/ -- Today, ThinkCP(TM) Announced the latest ThinkCP Storage Solution: the IceCube Mobile Storage Solution featuring up to 3.75 Terabytes of SATA RAID storage. The latest Think IceCube will be on display during GSA's International Products and Services Expo 2007 to be held at Orlando, Florida's Orange County Convention Center May 16th & 17th.

Price on the mobile IceCube3 varies depending on configuration from 1 Terabyte to 3.75 Terabytes. A 5 Terabyte version is also planned for release. Government customers will be able to purchase the storage solution listed on GSA's Schedule 70 directly from ThinkCP or from ThinkCP's Authorized VAR Partners. Additional specifications can be found at <http://www.ThinkCP.com/products/IceCube3.asp>.

ThinkCP(TM) also plans on exhibiting the latest ThinkCP(TM) ViPoR iSCSI XL SAN Solution (reported to be among the industry's fastest iSCSI solutions) and several of the latest ThinkCP FIDA SCI(TM) biometric fingerprint-based authentication tokens with optional digital identity support.

Federal customers in New Mexico will have the option of viewing the featured products and solutions at the NCSI New Mexico Technology Exhibits to be held May 21st through 24th at Los Alamos National Labs, White Sands Missile Range, Holloman Air Force Base and Kirtland Air Force Base, respectively.

About ThinkCP(TM)

Founded in 1987 and headquartered in Irvine,

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
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California, ThinkCP(TM) Technologies(TM) is an ISO 9001:2000 QMS accredited technology company specializing in custom design, integration and assembly of high-performance computing and storage solutions centered around the needs of enterprise class customers throughout the world. ThinkCP also partners with the industry's leading technology and service providers to deliver comprehensive solutions.

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CONTACT: Gary Richardson, V.P. of Sales & Marketing, ThinkCP,+1-949-428-7561, NewsInfo AT ThinkCP.com

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